

1025HC

Fast-acting, high current, surface mount ceramic tube fuses



Product description

- · Fast-acting high current fuse
- · Compact design utilizes less board space
- 20 A to 50 A current ratings
- Ceramic tube, silver plated brass end cap construction
- Halogen free and RoHS compliant

Applications

Primary and secondary circuit protection:

- · Server and desktop power supplies
- · Gaming console systems
- Voltage Regulator Module (VRM)
- · Storage system power
- · Base station power supplies
- Basic power supplies
- · LED and general lighting
- · Test equipment

Agency information

- cURus Recognition file number: E19180, Guide JDYX2/JDYX8
- PSE: JET 7042-31007-1002 (20 A to 30 A)

Ordering

• Use ordering number (see page 7 for details)

Packaging suffixes

 -TR (20 A to 30 A: 1500 parts per 13" diameter reel, tape width 24 mm) (40 A to 50 A: 1000 parts per 13" diameter reel, tape width 24 mm)



Electrical characteristics

| % of Amp Rating | Opening Time |
|-----------------|-----------------|
| 100 | 4 hours minimum |
| 200 | 60 s maximum |

Product specifications

| Part number ⁴ | Current rating (A) | Voltage rating (V _{AC}) | Voltage rating (V _{DC}) | Interrupting rating at rated voltage (A _{AC}) | Interrupting rating at rated voltage ¹ (A _{DC}) | Typical DC cold resistance 2 (m Ω) | Typical melting³ I²t (A²s) | Part marking | cURus | PSE |
|--------------------------|--------------------------|---|---|--|---|---|----------------------------------|------------------------------|-------|-----|
| 1025HC20-R | 20 | 250 | 72 | 100 | 500 | 3.1 | 25 | <ps> E JET BUSS 20A</ps> | Х | Х |
| 1025HC25-R | 25 | 250 | 72 | 100 | 500 | 2.6 | 50 | <ps> E JET BUSS 25A</ps> | Х | Х |
| 1025HC30-R | 30 | 250 | 72 | 100 | 500 | 1.7 | 112 | <ps> E JET BUSS 30A</ps> | Х | Х |
| 1025HC40-R | 40 | 250 | 72 | 300 | 500 | 1.3 | 400 | BUSS 40A | Х | |
| 1025HC50-R | 50 | 250 | 60 | 300 | 600 | 1.1 | 600 | BUSS 50A | Х | |

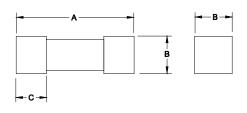
¹ DC interrupting rating measured at rated voltage, time constant of less than 1.0 microseconds, battery source

1025HC= Product code and size

xx= Ampere rating

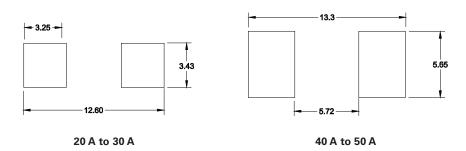
-R= Rohs compliant

Dimensions (mm)



| Rating | A | В | С |
|--------------|------------|------------|------------|
| 20 A to 30 A | 10.0 ±0.50 | 3.15 ±0.15 | 1.70 ±0.15 |
| 40 A to 50 A | 12.4 ±0.50 | 4.50 ±0.15 | 2.70 ±0.15 |

Recommended pad layout (mm)



Recommended trace thickness is 3 oz.

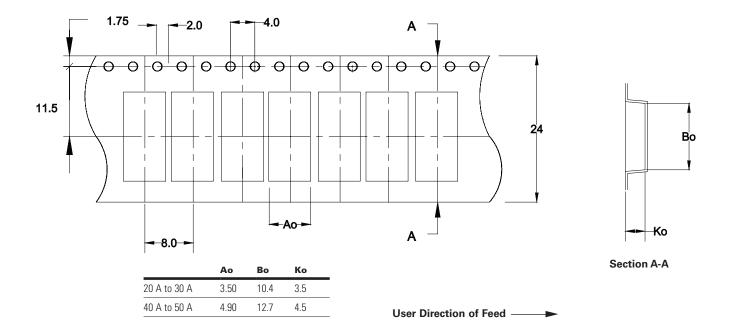
Recommended min-trace width is 10 mm (20 A to 30 A) and 15 mm (40 A to 50 A)

² Typical DC cold resistance measured at <10% of rated current at an ambient temperature of 20 °C (reference only)

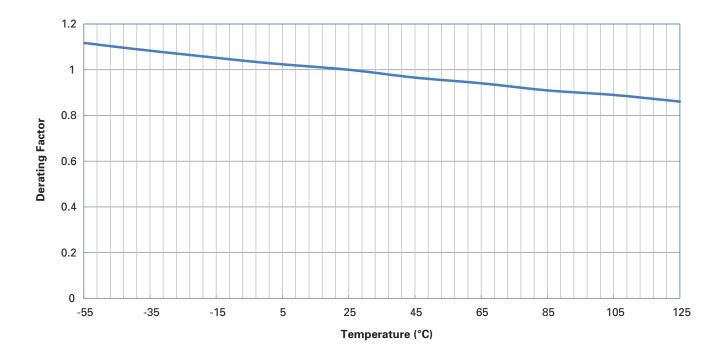
^{3.} Typical melting I2t value is measured at 10In rated current

^{4.} Part number definition: 1025HCxx-R

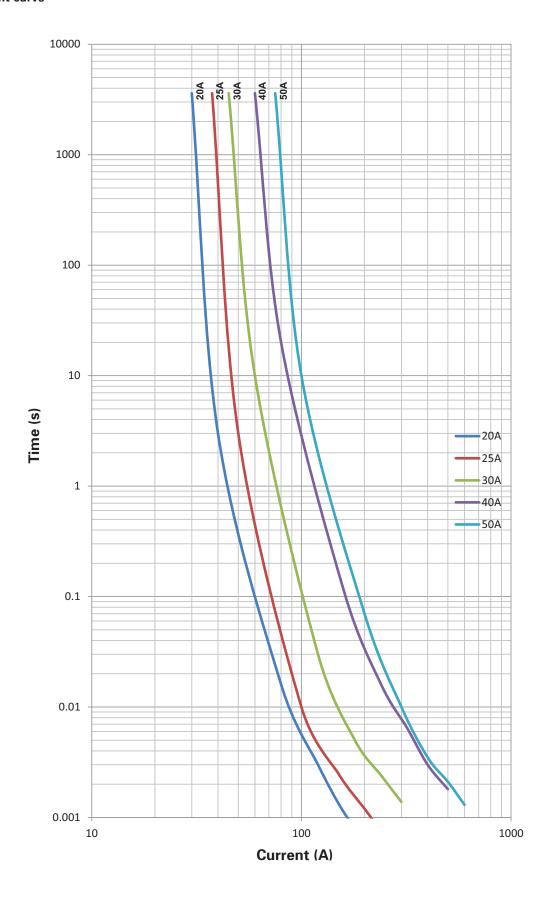
Packaging information (mm)



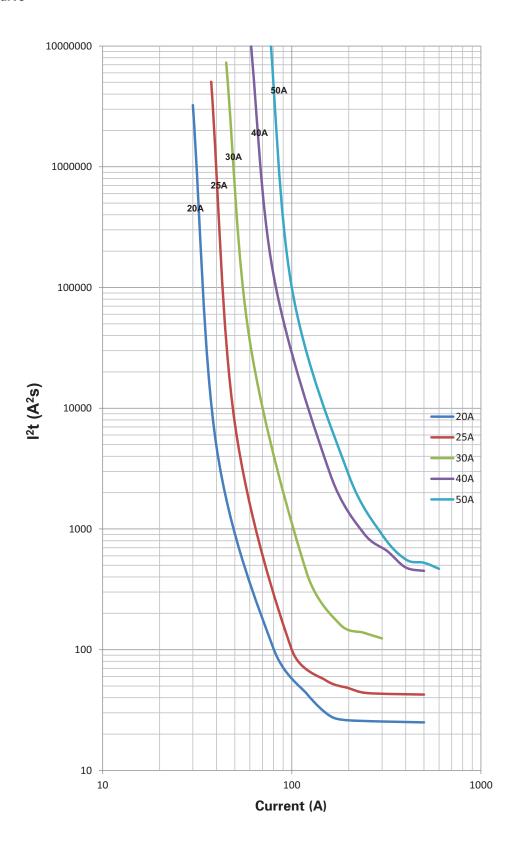
Temperature derating curve



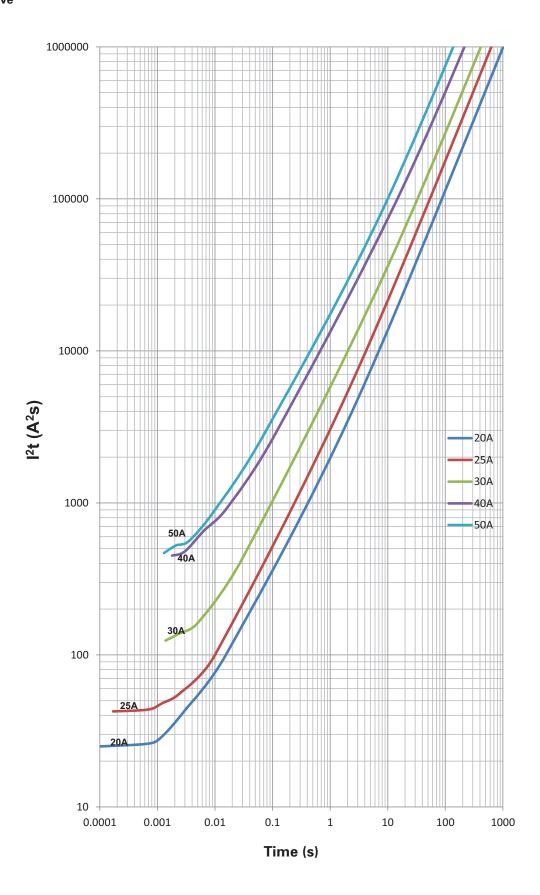
Time vs. current curve



l²t vs. current curve



I²t vs. time curve



Environmental data

| Operating temperature: - 55 °C to 125 °C (with derating) |
|--|
| Thermal cycling: (100 cycles - 55 °C to 125 °C) |
| Vibration: (20 g/s, 10 Hz - 2000 Hz) |
| Board flex: 60 s, 2 mm |
| Mechanical shock: 3000 g, 0.3 ms |
| Termination strength: 1.8 kg, 60 s |
| Solderability test: J-STD- 002, Method B1, G1 and D |
| |

Ordering codes

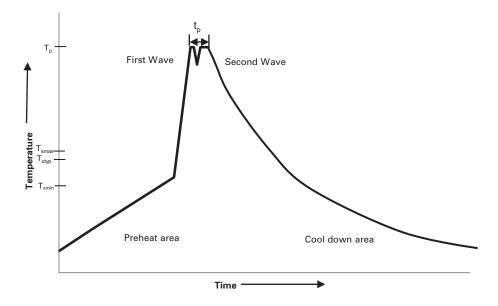
The ordering code is the part number adding the packaging suffix.

| | Ordering codes | |
|-------------|----------------|--|
| Part number | -TR option | |
| 1025HC20-R | 1025HC20-RTR | |
| 1025HC25-R | 1025HC25-RTR | |
| 1025HC30-R | 1025HC30-RTR | |
| 1025HC40-R | 1025HC40-RTR | |
| 1025HC50-R | 1025HC50-RTR | |

Packaging suffixes

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Wave solder profile

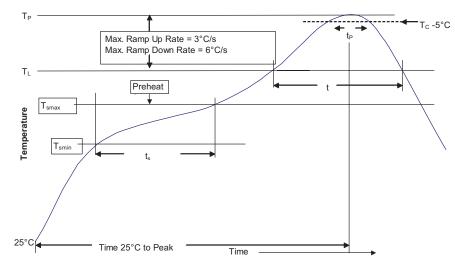


Reference EN 61760-1:2006

| Profile Feature | | Standard SnPb Solder | Lead (Pb) Free Solder | |
|---------------------|--|---|---|--|
| Preheat | • Temperature min. (T _{smin}) | 100 °C | 100 °C | |
| | Temperature typ. (T _{Styp}) | 120 °C | 120 °C | |
| | • Temperature max. (T _{smax}) | 130 °C | 130 °C | |
| | • Time (T _{smin} to T _{smax}) (t _s) | 70 seconds | 70 seconds | |
| Δ preheat to | max Temperature | 150 °C max. | 150 °C max. | |
| Peak tempera | ture (Tp)* | 235 °C − 260 °C | 250 °C − 260 °C | |
| Time at peak | temperature (t _p) | 10 seconds max 5 seconds max each wave | 10 seconds max 5 seconds max each wave | |
| Ramp-down ra | ate | ~ 2 K/s min ~3.5 K/s typ ~5 K/s max | ~ 2 K/s min ~3.5 K/s typ ~5 K/s max | |
| Time 25 °C to | 25 °C | 4 minutes | 4 minutes | |

Manual solder 350 °C, 4-5 seconds (by soldering iron), generally manual, hand soldering is not recommended.

Solder reflow profile



 $-_{\mathsf{T_C}}$ -5°C Table 1 - Standard SnPb Solder ($\mathsf{T_C}$)

| Package Thickness | Volume mm3 <350 | Volume mm3 ≥350 |
|----------------------|-----------------------|-----------------------|
| <2.5mm) | 235 °C | 220 °C |
| ≥2.5mm | 220 °C | 220 °C |

Table 2 - Lead (Pb) Free Solder (T_C)

| Package Thickness | Volume mm³ <350 | Volume mm³ 350 - 2000 | Volume mm³ >2000 |
|----------------------|-----------------------|-----------------------------|------------------------|
| <1.6mm | 260 °C | 260 °C | 260 °C |
| 1.6 – 2.5mm | 260 °C | 250 °C | 245 °C |
| >2.5mm | 250 °C | 245 °C | 245 °C |

Reference JDEC J-STD-020D

| Profile Feature | Standard SnPb Solder | Lead (Pb) Free Solder |
|---|--------------------------|--------------------------|
| Preheat and Soak • Temperature min. (T _{smin}) | 100 °C | 150 °C |
| • Temperature max. (T _{smax}) | 150 °C | 200 °C |
| • Time (T _{smin} to T _{smax}) (t _s) | 60-120 Seconds | 60-120 Seconds |
| Average ramp up rate T _{smax} to T _p | 3 °C/ Second Max. | 3 °C/ Second Max. |
| Liquidous temperature (TL) Time at liquidous (tL) | 183 °C 60-150 Seconds | 217 °C 60-150 Seconds |
| Peak package body temperature (Tp)* | Table 1 | Table 2 |
| Time $(t_p)^{**}$ within 5 °C of the specified classification temperature (T_c) | 20 Seconds** | 30 Seconds** |
| Average ramp-down rate (T _p to T _{smax}) | 6 °C/ Second Max. | 6 °C/ Second Max. |
| Time 25 °C to Peak Temperature | 6 Minutes Max. | 8 Minutes Max. |

^{*} Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

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^{**} Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.